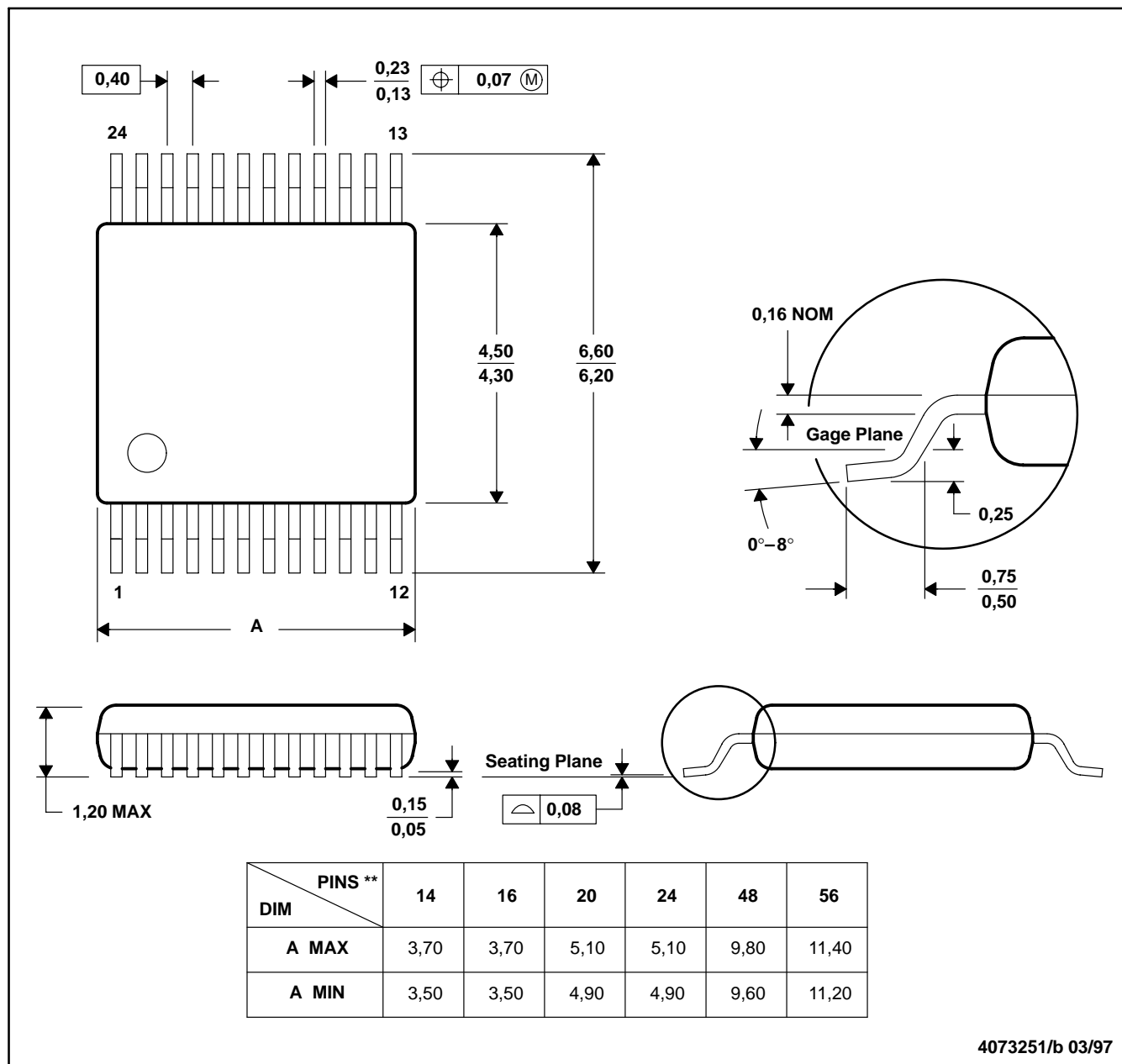


DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

24 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. The 24 and 48 pins falls within JEDEC MO-153 and the 14, 16, 20, and 56 pins falls within JEDEC MO-194.

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